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T. Bell
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Patent Application Serial No. 09/536,037
Filing Date March 27, 2000
Inventor Weimin Li et al.
Assignee Micron Technology, Inc.
Group Art Unit 2822
Examiner T. Thomas
Attorney's Docket No. MI22-1398
Title: Low K Interlevel Dielectric Layer Fabrication Methods

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

References -- See Attached Form PTO-1449

The attached Form PTO-1449 is submitted in compliance with 37 CFR § 1.56. Copies of the cited art are included herewith. No admission is made regarding whether all the submitted references are prior art.

This Supplemental Information Disclosure Statement is being filed with a Request for Continued Examination. Therefore, no fee is believed to be required. However, in the event that a fee is required for filing this Supplemental Information Disclosure Statement, please charge the fee specified under 37 C.F.R. §1.17(p) to Deposit Account No. 23-0925. Please credit Deposit Account No. 23-0925 with any overpayment of the above fee.

Citation of these references is respectfully requested.

Respectfully submitted,

Dated: 4-26-01

By: [Signature]
Mark S. Matkin
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